TPS3803−01
TPS3803G15
TPS3805H33

SLVS392A − JULY 2001 − REVISED JUNE 2007

VOLTAGE DETECTOR

FEATURES

- **Single Voltage Detector (TPS3803): Adjustable/1.5 V**
- **Dual Voltage Detector (TPS3805): Adjustable/3.3 V**
- **High ±1.5% Threshold Voltage Accuracy**
- **Supply Current: 3 μA Typical at V_{DD} = 3.3 V**
- **Push/Pull Reset Output (TPS3805) Open-Drain Reset Output (TPS3803)**
- **Temperature Range: −40°C to +85°C**
- **5-Pin SC−70 Package**

APPLICATIONS

- **Applications Using DSPs, Microcontrollers, or Microprocessors**
- **Wireless Communication Systems**
- **Portable/Battery-Powered Equipment**
- **Programmable Controls**
- **Intelligent Instruments**
- **Industrial Equipment**
- **Notebook/Desktop Computers**
- **Automotive Systems**

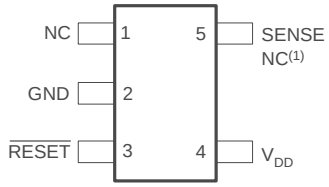
DESCRIPTION

The TPS3803 and TPS3805 families of supervisory circuits provide circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

The TPS3803G15 device has a fixed-sense threshold voltage V_{IT} set by an internal voltage divider, whereas the TPS3803−01 has an adjustable SENSE input that can be configured by two external resistors. In addition to the fixed sense threshold monitored at V_{DD}, the TPS3805 devices provide a second adjustable SENSE input. $\overline{\text{RESET}}$ is asserted in case any of the two voltages drops below V_{IT}.

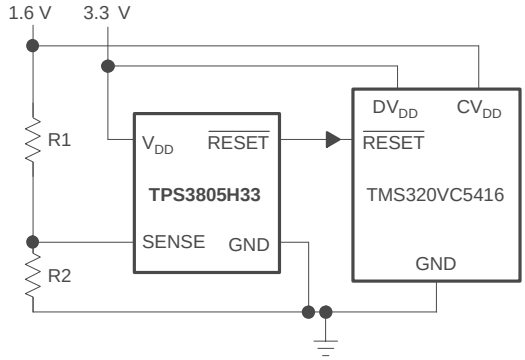
During power on, $\overline{\text{RESET}}$ is asserted when supply voltage V_{DD} becomes higher than 0.8 V. Thereafter, the supervisory circuit monitors V_{DD} (and/or SENSE) and keeps $\overline{\text{RESET}}$ active as long as V_{DD} or SENSE remains below the threshold voltage V_{IT}. As soon as V_{DD} (SENSE) rises above the threshold voltage V_{IT}, $\overline{\text{RESET}}$ is deasserted again. The product spectrum is designed for 1.5 V, 3.3 V, and adjustable supply voltages. The devices are available in a 5-pin SC-70 package. The TPS3803 and TPS3805 devices are characterized for operation over a temperature range of −40°C to +85°C.

DCK PACKAGE
(Top View)
TPS3803-01, TPS3803G15, TPS3805



(1) NC = No Connection on **TPS3803G15**

Typical Operating Circuit



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

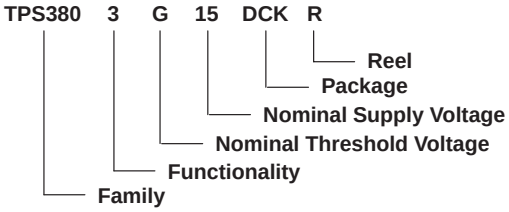
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE INFORMATION

T_A	DEVICE NAME	THRESHOLD VOLTAGE		MARKING
		V_{DD}	SENSE	
−40°C to +85°C	TPS3803−01DCKR(1)	NA	1.226 V	AWG
	TPS3803G15DCKR(1)	1.40 V	NA	AWI
	TPS3805H33DCKR(1)	3.05 V	1.226 V	AWK

(1) The DCKR passive indicates tape and reel containing 3000 parts.

ORDERING INFORMATION

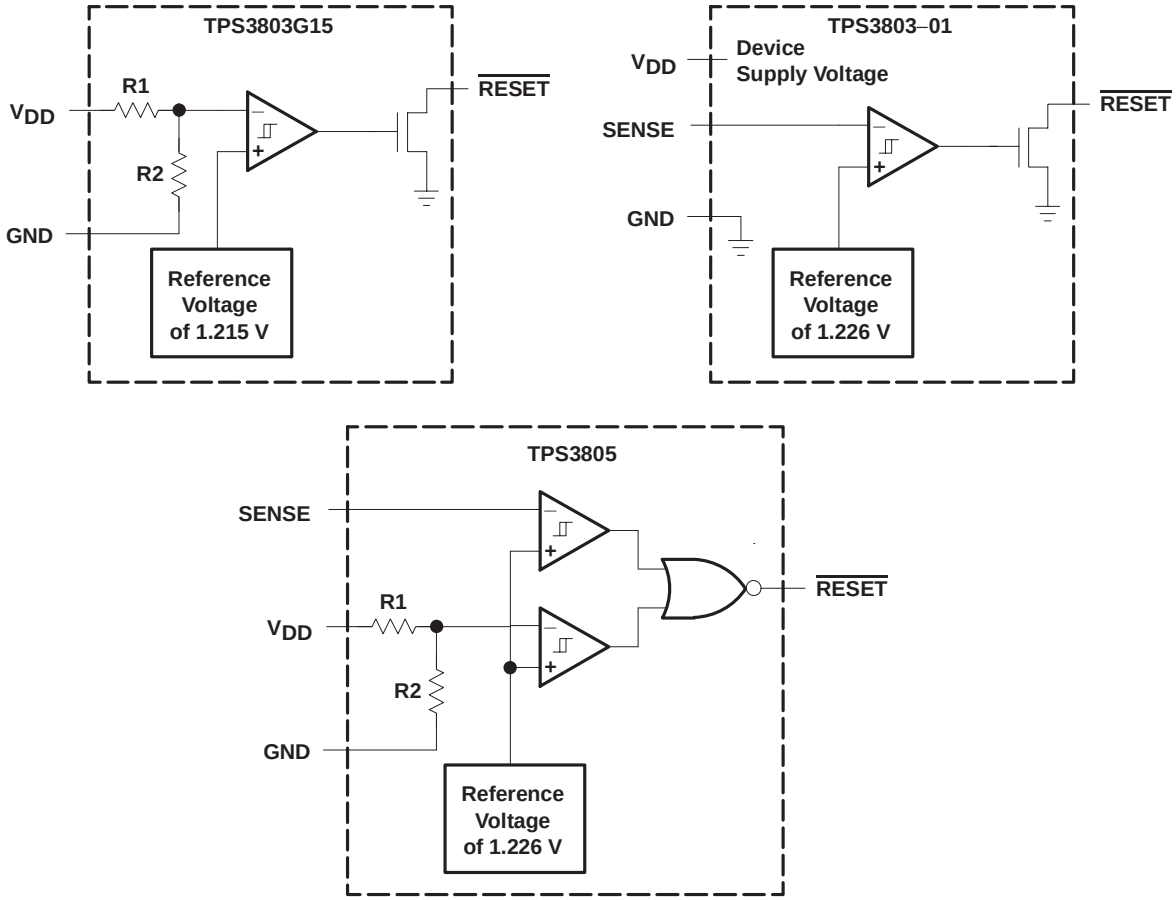


Function/Truth Tables

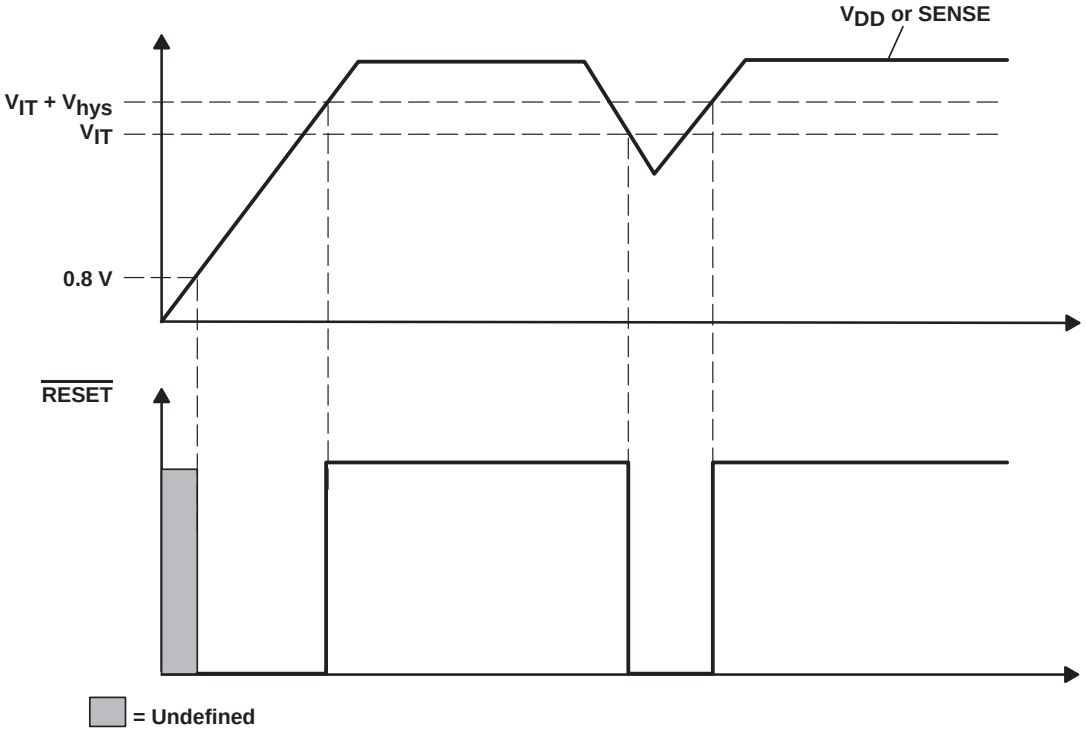
TPS3803-01		TPS3803G15	
SENSE > V_{IT}	$\overline{\text{RESET}}$	V_{DD} > V_{IT}	$\overline{\text{RESET}}$
0	L	0	L
1	H	1	H

TPS3805H33		
V_{DD} > V_{IT}	SENSE > V_{IT}	$\overline{\text{RESET}}$
0	0	L
0	1	L
1	0	L
1	1	H

FUNCTIONAL BLOCK DIAGRAM



TIMING REQUIREMENTS



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
GND	2	I	Ground
$\overline{\text{RESET}}$	3	O	Active-low reset output (TPS3803—open−drain, TPS3805—push/pull)
SENSE	5	I	Adjustable sense input
NC	1		No internal connection
NC (TPS3803G15)	5		No internal connection
V_{DD}	4	I	Input supply voltage, fixed sense input for TPS3803G15 and TPS3805

ABSOLUTE MAXIMUM RATINGS(1)

Over operating free-air temperature range, unless otherwise noted.

Supply voltage, V_{DD}(2) . . . . . +7 V
All other pins(2) . . . . . −0.3 V to +7 V
Maximum low-output current, I_{OL} . . . . . +5 mA
Maximum high-output current, I_{OH} . . . . . −5 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$) . . . . . ±10 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$) . . . . . ±10 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . −40°C to +85°C
Storage temperature range, T_{stg} . . . . . −65°C to +150°C
Soldering temperature . . . . . +260°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute−maximum−rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to GND. For reliable operation the device should not be continuously operated at 7 V for more than t = 1000 h.

DISSIPATION RATING TABLE

PACKAGE	T_A < +25°C POWER RATING	DERATING FACTOR ABOVE T_A = +25°C	T_A = +70°C POWER RATING	T_A = +85°C POWER RATING
DCK	321 mW	2.6 mW/°C	206 mW	167 mW

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, V_{DD}	1.3	6	V
Input voltage, V_I	0	V_{DD} + 0.3	V
Operating free-air temperature range, T_A	−40	85	°C

ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range, unless otherwise noted.

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage (TPS3805 only)		V_{DD} = 1.5 V, I_{OH} = −0.5 mA	0.8 x V_{DD}			V
			V_{DD} = 3.3 V, I_{OH} = −1.0 mA				
			V_{DD} = 6 V, I_{OH} = −1.5 mA				
V_{OL}	Low-level output voltage		V_{DD} = 1.5 V, I_{OL} = 1.0 mA				V
			V_{DD} = 3.3 V, I_{OL} = 2 mA			0.3	
			V_{DD} = 6 V, I_{OL} = 3 mA				
	Power-up reset voltage(1)	V_{IT} > 1.5 V, T_A = 25°C		0.8			V
		V_{IT} ≤ 1.5 V, T_A = 25°C		1.0			V
V_{IT}	Negative-going input threshold voltage(2)	SENSE	T_A = −40°C to +85°C	1.208	1.226	1.244	V
		TPS3803G15		1.379	1.4	1.421	
		TPS3805H33		3.004	3.05	3.096	
V_{hys}	Hysteresis		1.2 V < V_{IT} < 2.5 V		15		mV
			2.5 V < V_{IT} < 3.5 V		30		
I_I	Input current	SENSE		−25		25	nA
I_{OH}	High-level output current at $\overline{\text{RESET}}$	Open drain only	V_{DD} = V_{IT} + 0.2V, V_{OH} = V_{DD}			300	nA
I_{DD}	Supply current	TPS3803−01	V_{DD} = 3.3 V, output unconnected		2	4	µA
		TPS3805, TPS3803G15			3	5	
		TPS3803−01	V_{DD} = 6 V, output unconnected		2	4	
		TPS3805, TPS3803G15			4	6	
C_I	Input capacitance		V_I = 0 V to V_{DD}		1		pF

(1) The lowest supply voltage at which $\overline{\text{RESET}}$ (V_{OL}(max) = 0.2 V, I_{OL} = 50 µA) becomes active. $t_{r(VDD)}$ ≥ 15 µs/V.
(2) To ensure the best stability of the threshold voltage, place a bypass capacitor (ceramic, 0.1 µF) near the supply terminals.

TIMING REQUIREMENTS

AT R_L = 1 MΩ, C_L = 50 PF, T_A = −40°C TO +85°C.

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Pulse width	At V_{DD}	V_{IH} = 1.05 x V_{IT}, V_{IL} = 0.95 x V_{IT}	5.5			µs
		At SENSE					

SWITCHING CHARACTERISTICS

AT R_L = 1 MΩ, C_L = 50 PF, T_A = −40°C TO +85°C.

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation (delay) time, high-to-low-level output	V_{DD} to $\overline{\text{RESET}}$ delay	V_{IH} = 1.05 x V_{IT}, V_{IL} = 0.95 x V_{IT}		5	100	µs
		SENSE to $\overline{\text{RESET}}$ delay					
t_{PLH}	Propagation (delay) time, low-to-high-level output	V_{DD} to $\overline{\text{RESET}}$ delay			5	100	
		SENSE to $\overline{\text{RESET}}$ delay					

TYPICAL CHARACTERISTICS

TPS3805H33
SUPPLY CURRENT
vs
SUPPLY VOLTAGE

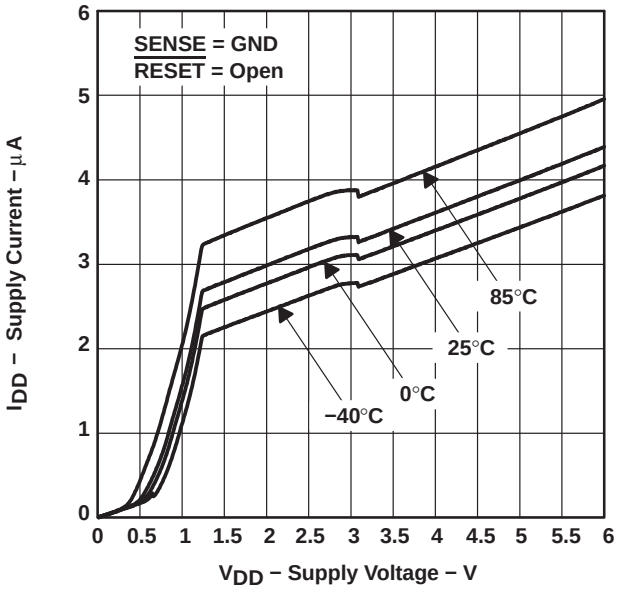


Figure 1

TPS3803−01
SUPPLY CURRENT
vs
SUPPLY VOLTAGE

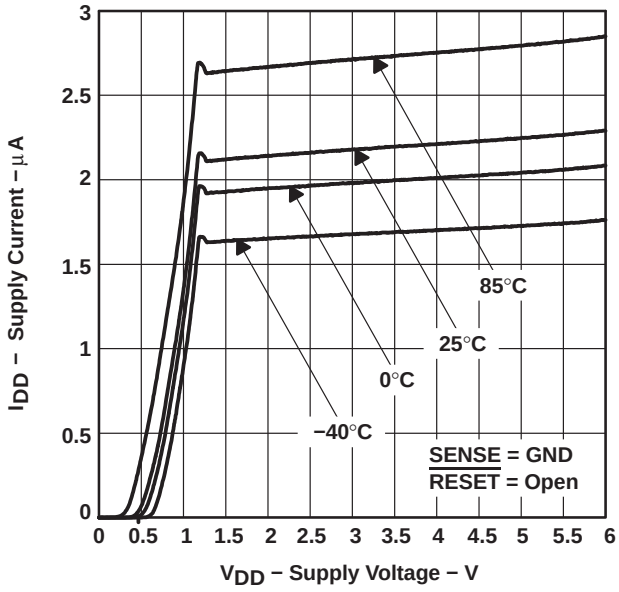


Figure 2

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

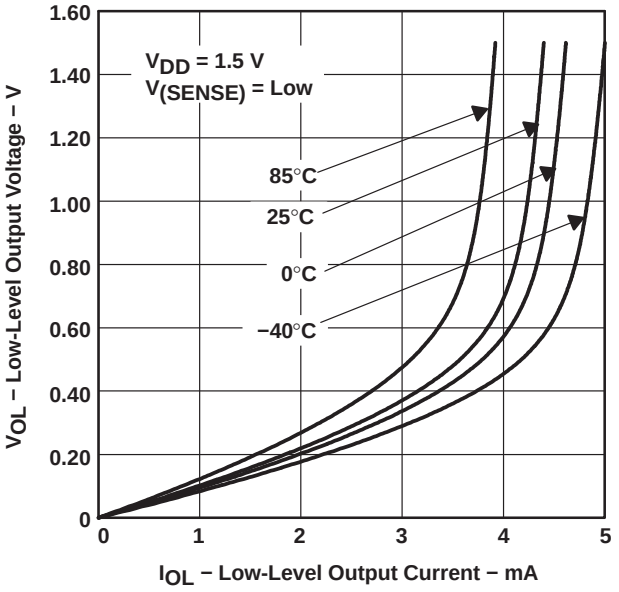


Figure 3

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

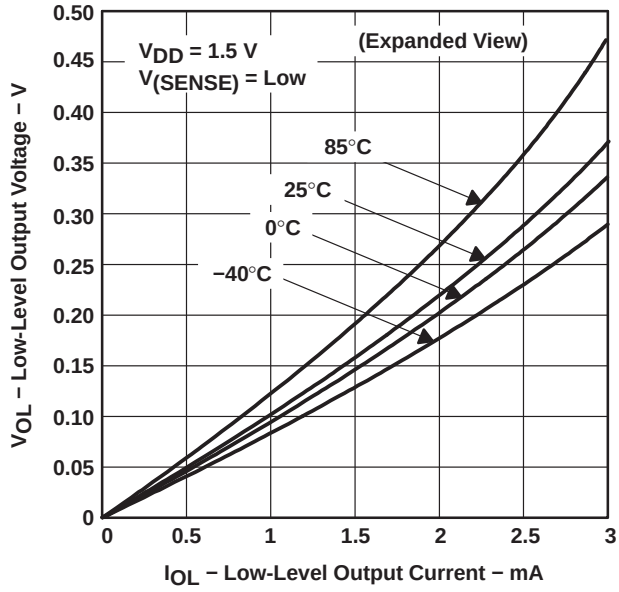


Figure 4

TYPICAL CHARACTERISTICS (continued)

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

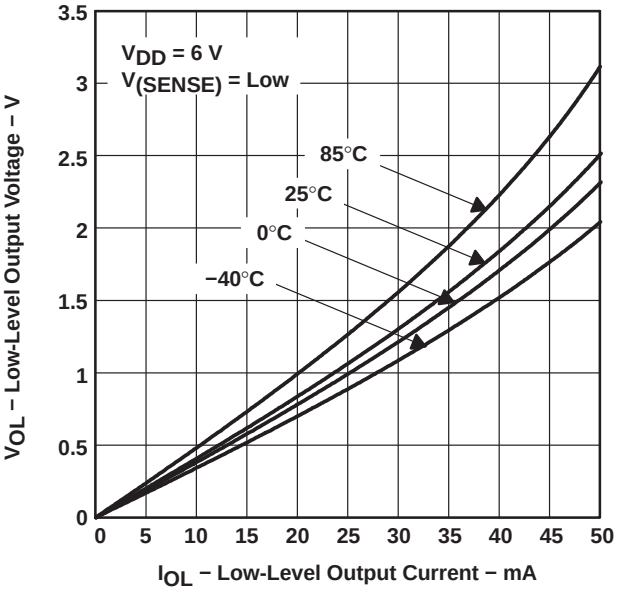


Figure 5

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

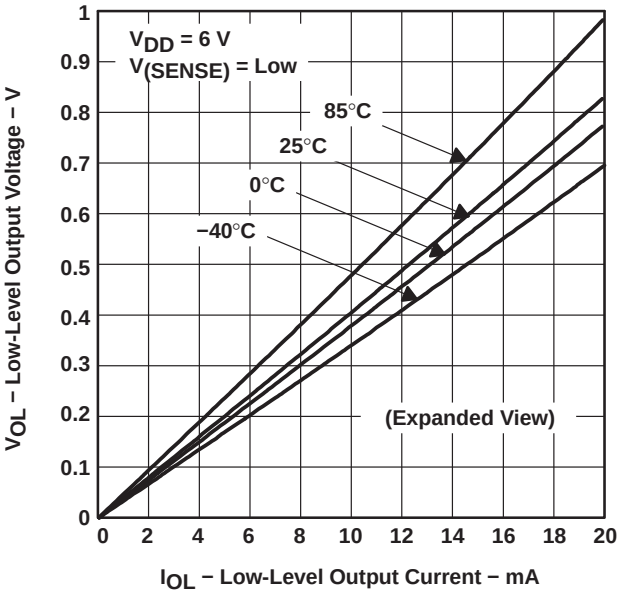


Figure 6

TPS3805H33
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

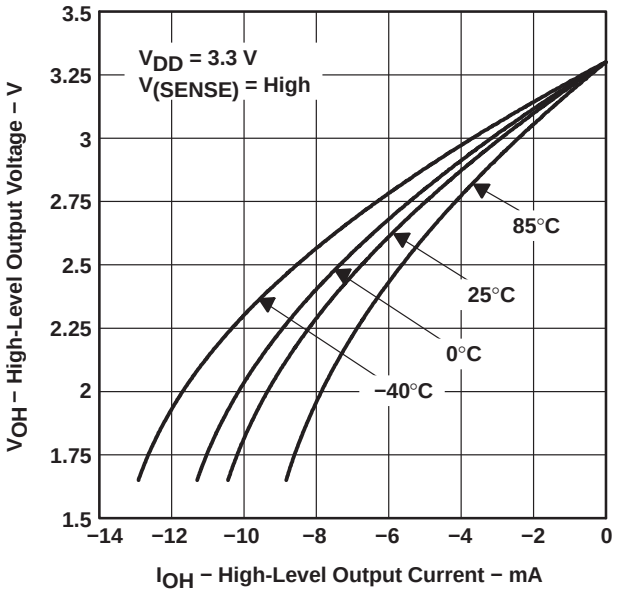


Figure 7

TPS3805H33
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

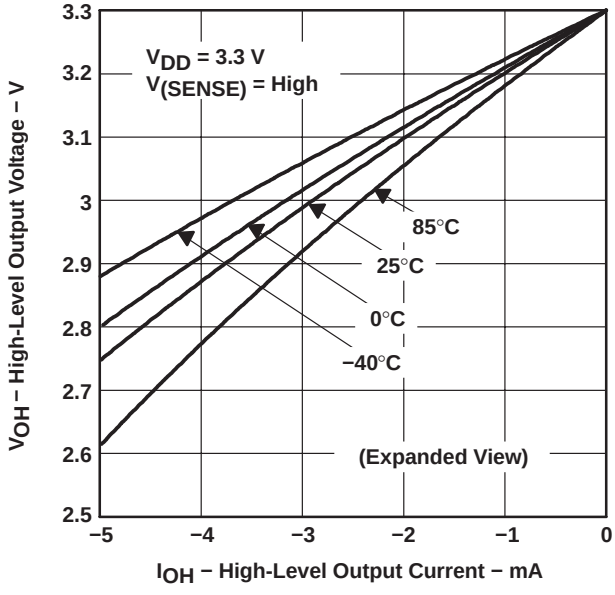


Figure 8

TYPICAL CHARACTERISTICS (continued)

TPS3805H33
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

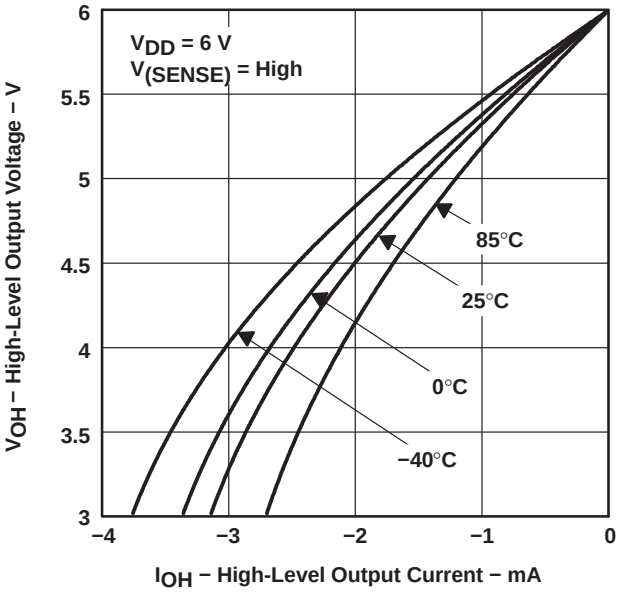


Figure 9

TPS3805H33
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

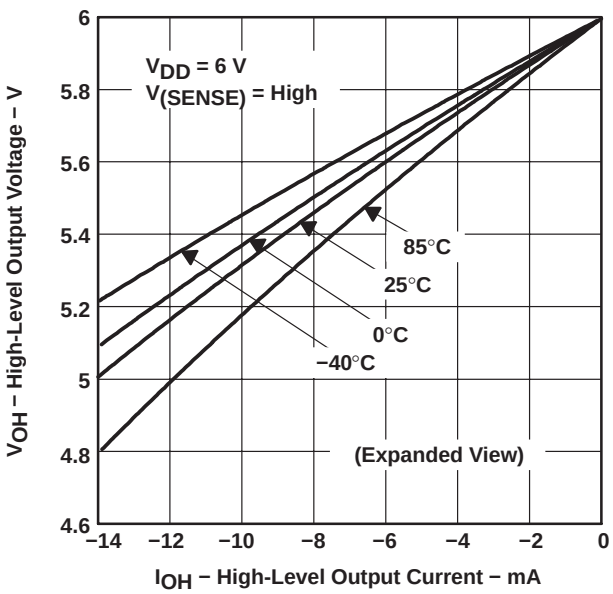


Figure 10

TPS3803−01
NORMALIZED INPUT THRESHOLD VOLTAGE
vs
FREE-AIR TEMPERATURE AT SENSE

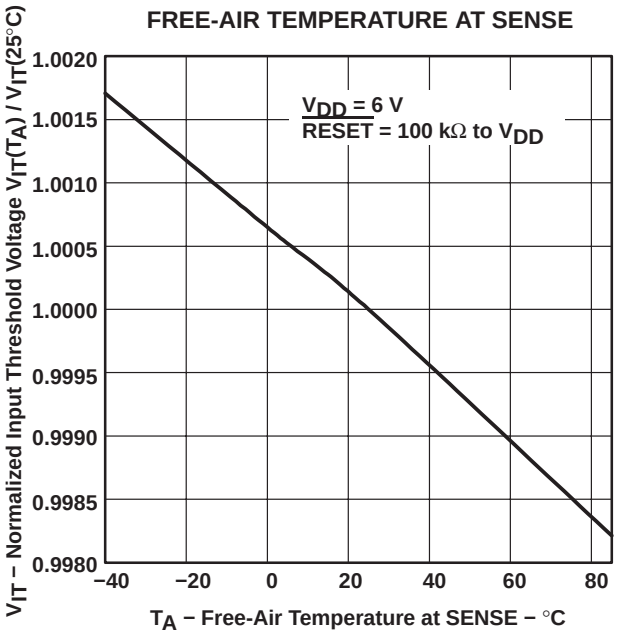


Figure 11

MINIMUM PULSE DURATION AT V_{DD}
vs
V_{DD} THRESHOLD OVERDRIVE VOLTAGE

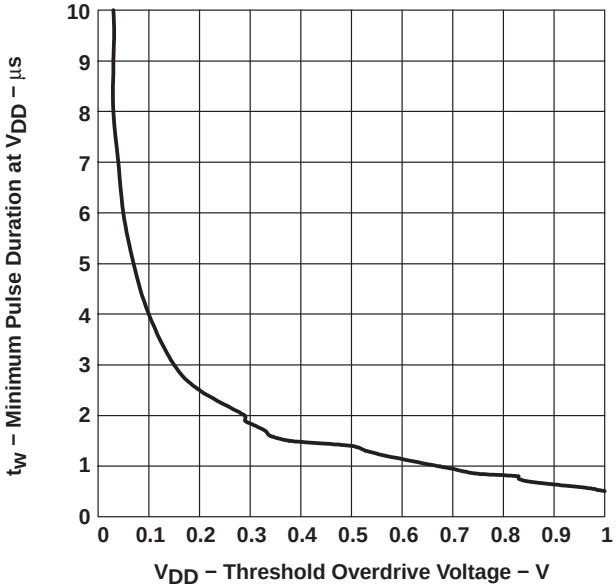


Figure 12

TYPICAL CHARACTERISTICS (continued)

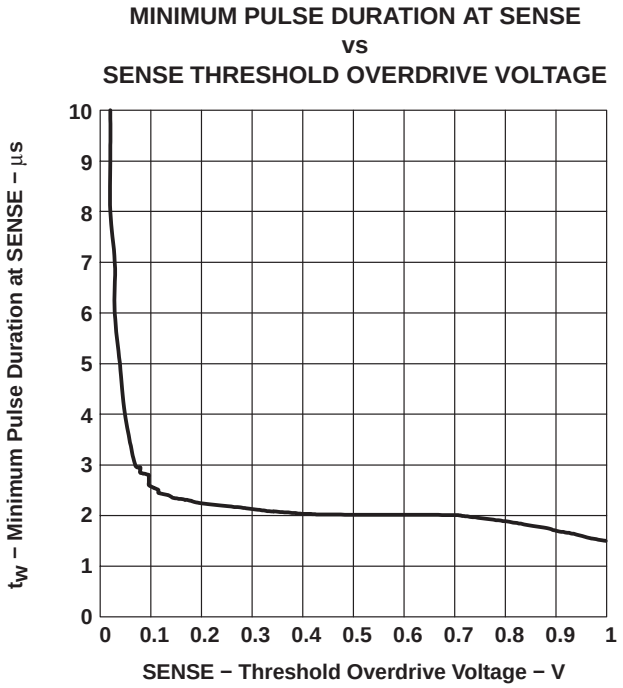


Figure 13

Revision History

DATE	REV	PAGE	SECTION	DESCRIPTION
6/07	A	Front Page	—	Updated front page.
		3	—	Functional block diagram change.

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3803-01DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	AWG	Samples
TPS3803-01DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	AWG	Samples
TPS3803G15DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM		AWI	Samples
TPS3803G15DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM		AWI	Samples
TPS3805H33DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	AWK	Samples
TPS3805H33DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	AWK	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF TPS3803-01, TPS3803G15, TPS3805H33 :

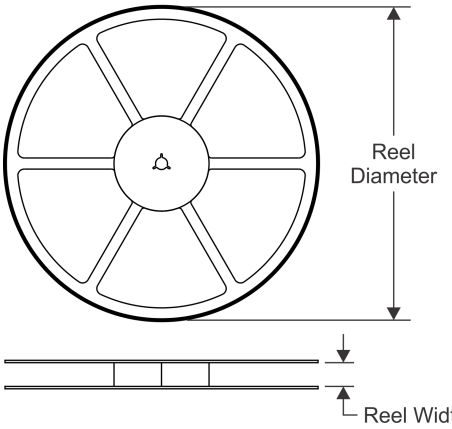
- Automotive: TPS3803-01-Q1, TPS3803G15-Q1, TPS3805H33-Q1
- Enhanced Product: TPS3803-01-EP, TPS3803G15-EP, TPS3805H33-EP

NOTE: Qualified Version Definitions:

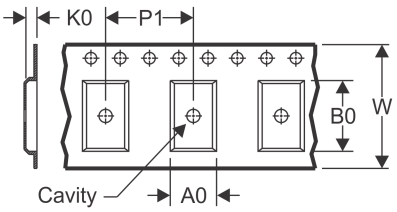
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

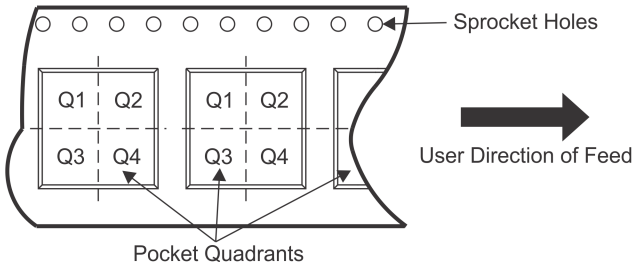


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

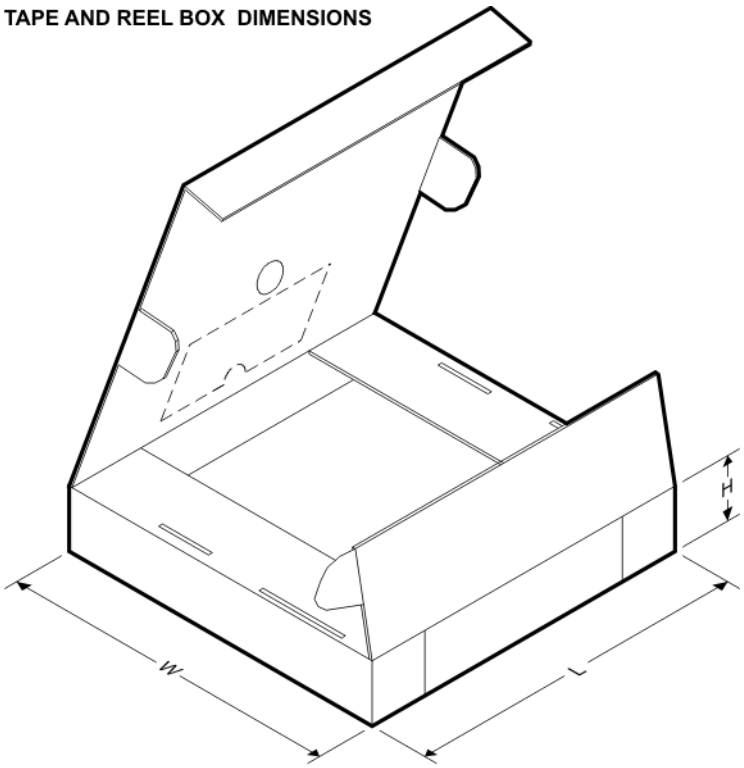
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3803-01DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3803-01DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3803G15DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3805H33DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3805H33DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3

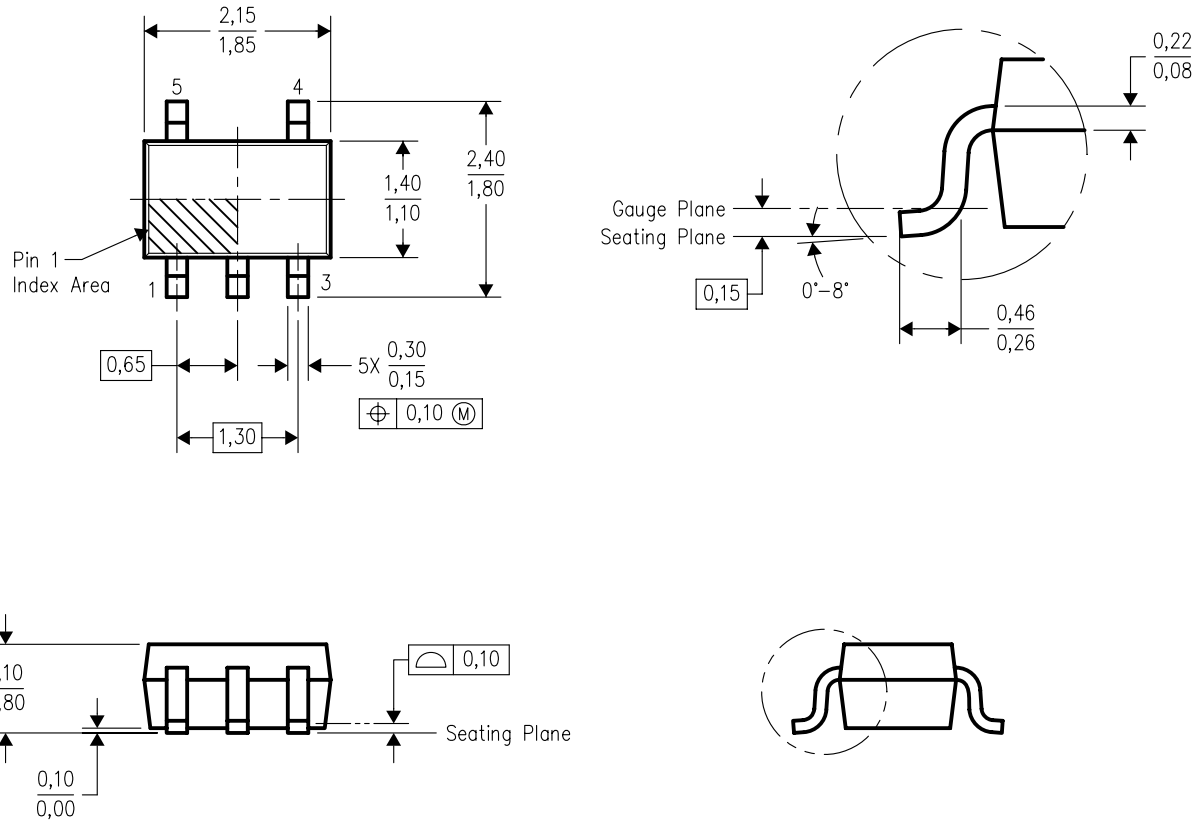
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3803-01DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3803-01DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3803G15DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3805H33DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3805H33DCKR	SC70	DCK	5	3000	202.0	201.0	28.0

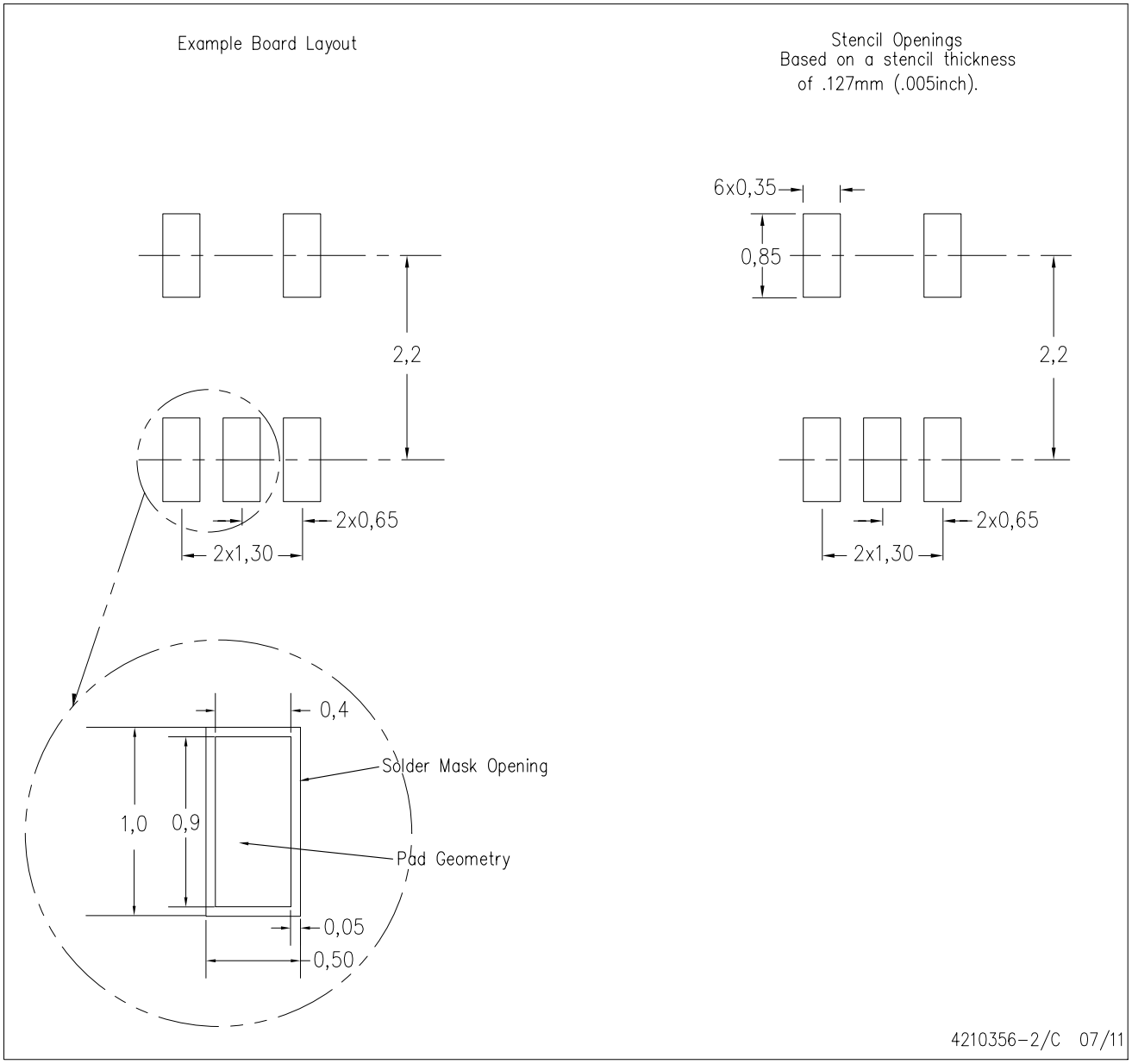
DCK (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



4093553–3/G 01/2007

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AA.

DCK (R–PDSO–G5) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

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